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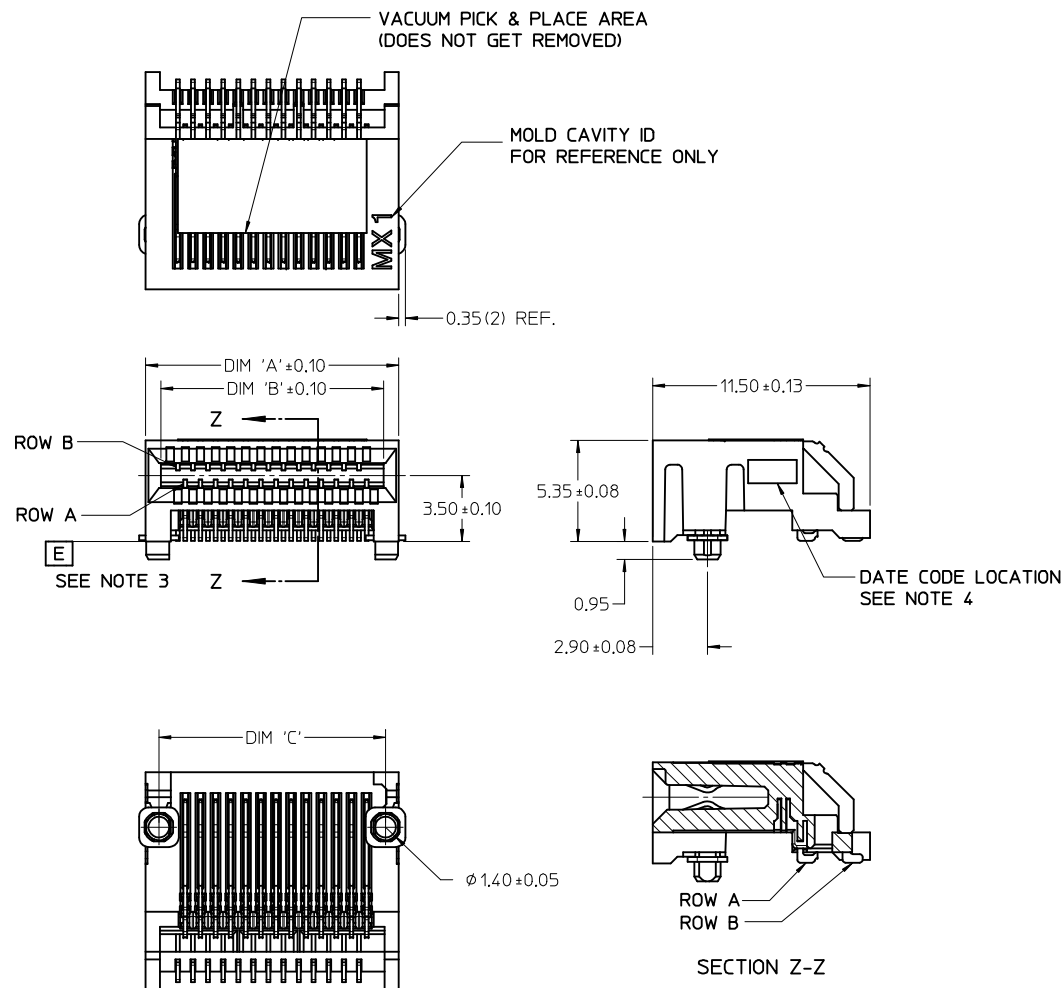
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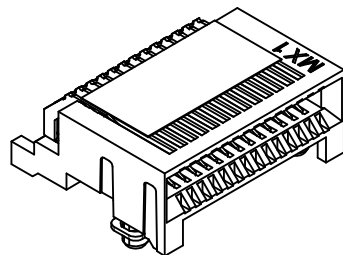
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CIRCUIT SIZE	ITEM NUMBER	PLATING OPTION	DIM 'A'	DIM 'B'	DIM 'C'
26	75586-0101	OPTION 1	13.40	11.80	12.00
26	75586-0102	OPTION 2	13.40	11.80	12.00
38	75586-0103	OPTION 1	18.20	16.60	16.80
38	75586-0104	OPTION 2	18.20	16.60	16.80
68	75586-0105	OPTION 1	30.20	28.60	28.80
68	75586-0106	OPTION 2	30.20	28.60	28.80

NOTES

- MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED,
UL 94V-0, BLACK
TERMINALS - COPPER ALLOY
- PLATING:
OPTION 1
CONTACT AREA - 0.38 μm MIN GOLD OVER 2.54 μm MIN NICKEL
SOLDER FOOT AREA - 2.54 - 5.09 μm TIN OVER 1.27 μm MIN NICKEL.
OPTION 2
CONTACT AREA - 0.76 μm MIN GOLD OVER 2.54 μm NICKEL
SOLDER AREA - 2.54 - 5.09 μm TIN OVER 1.27 μm MIN NICKEL
- TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/004 MEASURED FROM FRONT HOUSING STAND OFF (DATUM E)
- DATE CODE: 4 DIGIT (3 DIGIT DATE, 1 DIGIT YEAR)
- CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1
- TO BE USED WITH EXTERNAL CABLES (74546 & 74547 SERIES) AND GUIDE FRAMES (74540 & 74548 SERIES)
- TESTER/ANALYZER CABLES AVAILABLE (74557 & 74558 SERIES)
- PACKAGED PER PACKAGING SPECIFICATION: PK-75586-002
- CONFORMS TO PRODUCT SPECIFICATION: PS-75586-001
- THIS PART CONFORMS TO CLASS C REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



REV NOTE 2 EC NO: UCP2015-0453 DRAWN BY: INGHAM 2014/07/31 CHKD: TMCLELLAND 2014/08/01 APPR: TMCLELLAND 2014/08/01		DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING molex	
					mm	INCH	DRAWN BY	DATE	DOCUMENT NO. SD-75586-005			
				4 PLACES	± ---	± ---	KLANG	12/06/2006				
				3 PLACES	± ---	± ---	CHECKED BY	DATE				
				2 PLACES	± 0.13	± ---	JSWENSON	12/06/2006				
				1 PLACE	± 0.25	± ---	APPROVED BY	DATE				
0 PLACE	±	±	MBANAKIS	12/06/2006	SHEET NO. 1 OF 6							
C2	REV			ANGULAR ±1/2°		MATERIAL NO.						
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART						
				SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

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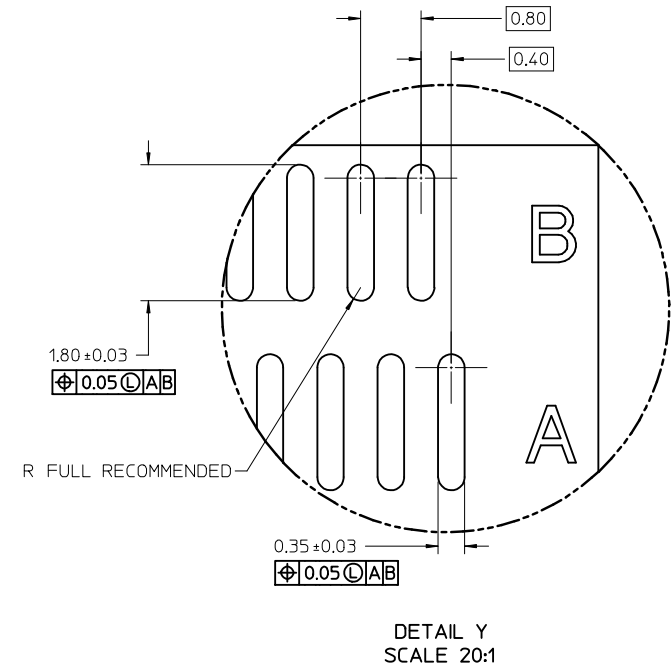
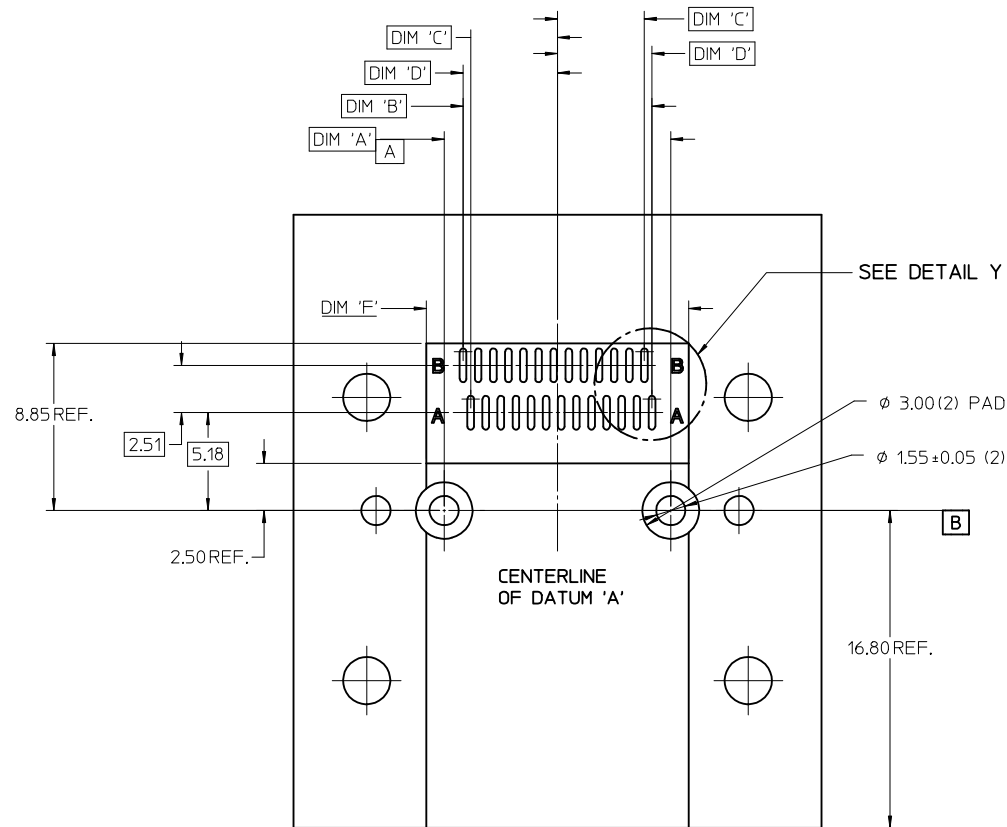
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MOTHERBOARD FOOTPRINT RECOMMENDATION

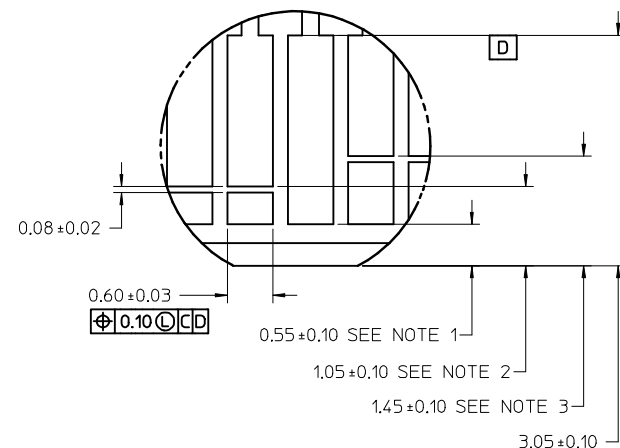
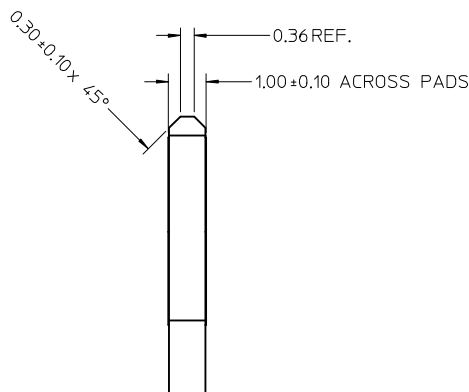
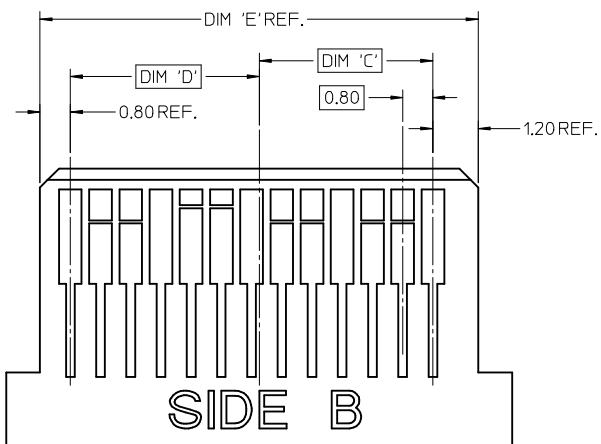
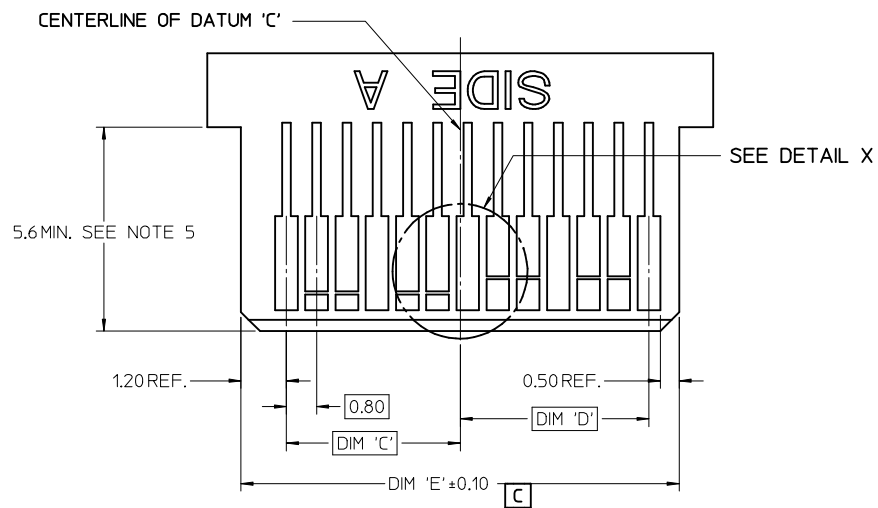


- NOTES:**
- SEE 74540 OR 74548 SERIES FOR GUIDE FRAME FOOT PRINT AND KEEP OUT AREA.

		PEG TO PEG	FIRST PAD TO LAST PAD	CENTERLINE TO PAD	CENTERLINE TO PAD	MODULE BOARD WIDTH	CONNECTOR WIDTH
CIRCUIT SIZE	TERM/SIDE 'N'	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'
26	13	12.00	10.00	4.60	5.00	11.60	13.90
38	19	16.80	14.80	7.00	7.40	16.40	18.70
68	34	28.80	26.80	13.00	13.40	28.40	30.70

SEE SHEET 1 EC NO: UCP2015-0453 C2 DRAWN BY: INGHAM 2014/07/31 CHKD: TMCLELLAND 2014/08/01 APPR: TMCLELL 2014/08/01	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				mm	INCH	DRAWN BY KLANG		DATE 12/06/2006	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING molex				
			4 PLACES	± ---	± ---	CHECKED BY JSWENSON		DATE 12/06/2006					
			3 PLACES	± ---	± ---	APPROVED BY MBANAKIS		DATE 12/06/2006	DOCUMENT NO. SD-75586-005				
			2 PLACES	± 0.13	± ---	MATERIAL NO.							
			1 PLACE	± 0.25	± ---	SEE CHART			SHEET NO. 2 OF 6				
			0 PLACE	±	±	SIZE							
			ANGULAR ±1/2°			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS										
			REV										

MODULE BOARD FOOTPRINT RECOMMENDATION



DETAIL X
SCALE 20:1

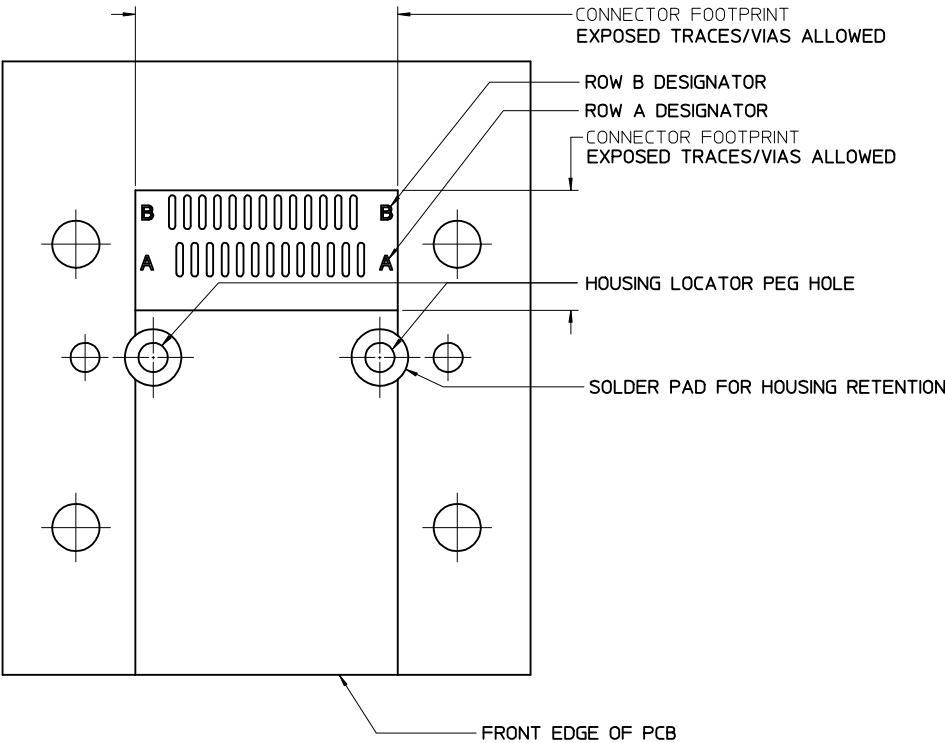
NOTES:

- PAD CONFIGURATION FOR FIRST MATE.
- PAD CONFIGURATION FOR SECOND MATE.
- PAD CONFIGURATION FOR THIRD MATE (HIGH SPEED SIGNALS).
- FOR PIN ASSIGNMENTS AND MATING SEQUENCE (1ST, 2ND, 3RD), SEE APPLICABLE SPECIFICATION.
- MINIMUM STEP REQUIRED IF PCB MADE WIDER THAN CARD TONGUE.

CIRCUIT SIZE	TERM/SIDE 'N'	CENTERLINE TO PAD			MODULE BOARD WIDTH
		DIM 'C'	DIM 'D'	DIM 'E'	
26	13	4.60	5.00	11.60	
38	19	7.00	7.40	16.40	
68	34	13.00	13.40	28.40	

SEE SHEET 1 EC NO: UCP2015-0453 DRAWN BY: DRWNBINGHAM 2014/07/31 CHKD: TMCLELLAND 2014/08/01 APPR: TMCLELL 2014/08/01 C2	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
				mm	INCH	DRAWN BY KLANG	DATE 12/06/2006	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING		
			4 PLACES ± ---	± ---	CHECKED BY JSWENSON	DATE 12/06/2006				
			3 PLACES ± ---	± ---	APPROVED BY MBANAKIS	DATE 12/06/2006				
			2 PLACES ± 0.13	± ---	MATERIAL NO.			DOCUMENT NO.		SHEET NO.
			1 PLACE ± 0.25	± ---	SEE CHART			SD-75586-005		3 OF 6
			0 PLACE ±	±						
			ANGULAR ±1/2°							
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							
			REV							

CONNECTOR FOOTPRINT ZONE IDENTIFICATION



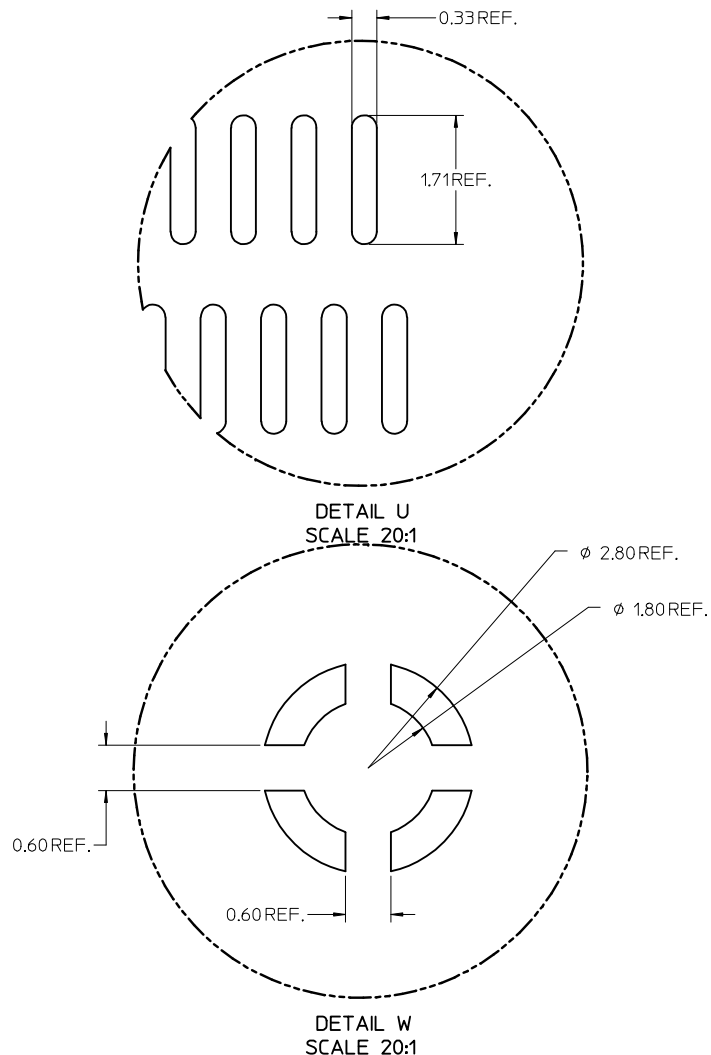
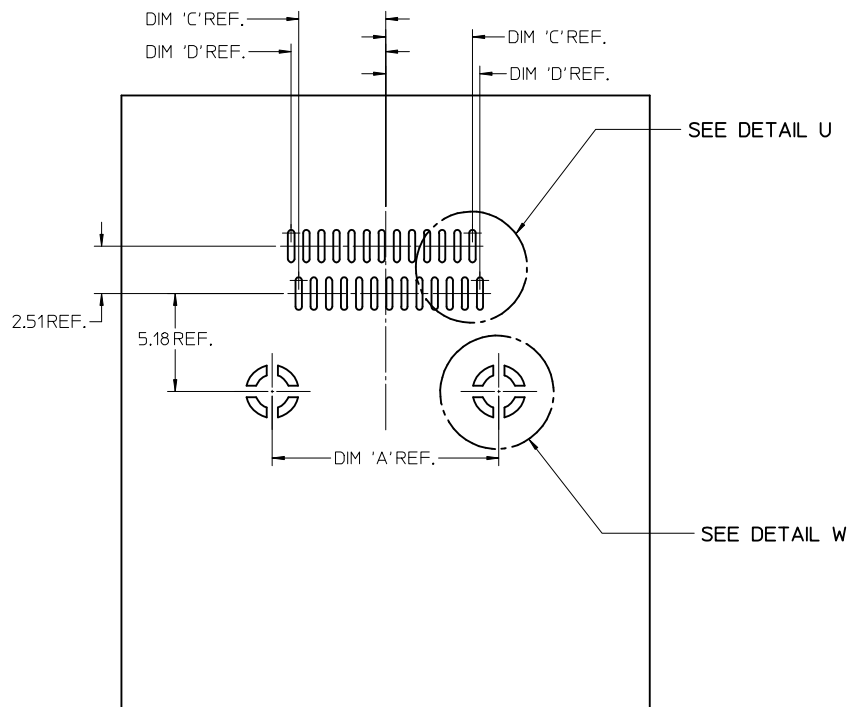
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					mm	INCH	DRAWN BY KLANG		DATE 12/06/2006			
				4 PLACES	± ---	± ---	CHECKED BY JSWENSON		DATE 12/06/2006			
				3 PLACES	± ---	± ---	APPROVED BY MBANAKIS		DATE 12/06/2006			
				2 PLACES	± 0.13	± ---	MATERIAL NO.		DOCUMENT NO.			
				1 PLACE	± 0.25	± ---	SEE CHART		SD-75586-005			
				0 PLACE	±	±	SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
				ANGULAR ±1/2°				SHEET NO. 4 OF 6				
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								

NOTES:

- 1. STENCIL RECOMMENDATION IS A GUIDELINE ONLY.
- 2. MANUFACTURING PROCESS PARAMETERS WILL DEFINE THE ACTUAL STENCIL DEFINITION.
- 3. RECOMMENDED STENCIL THICKNESS IS 0.13MM.

SOLDER STENCIL RECOMMENDATION

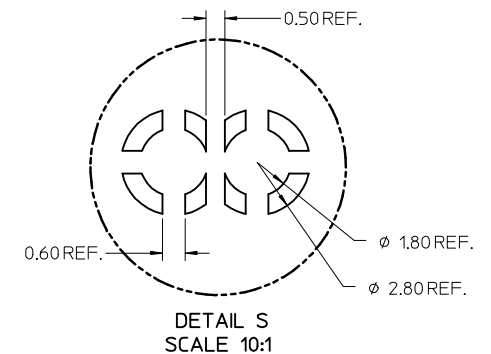
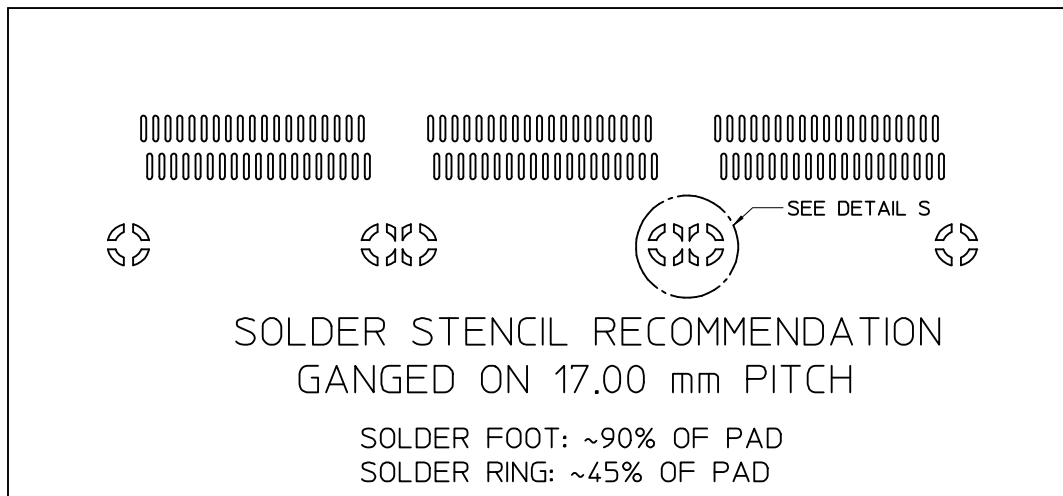
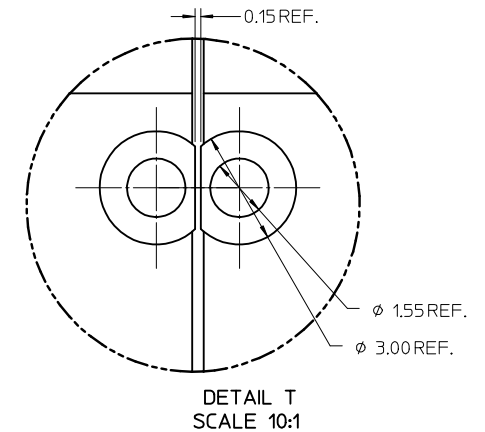
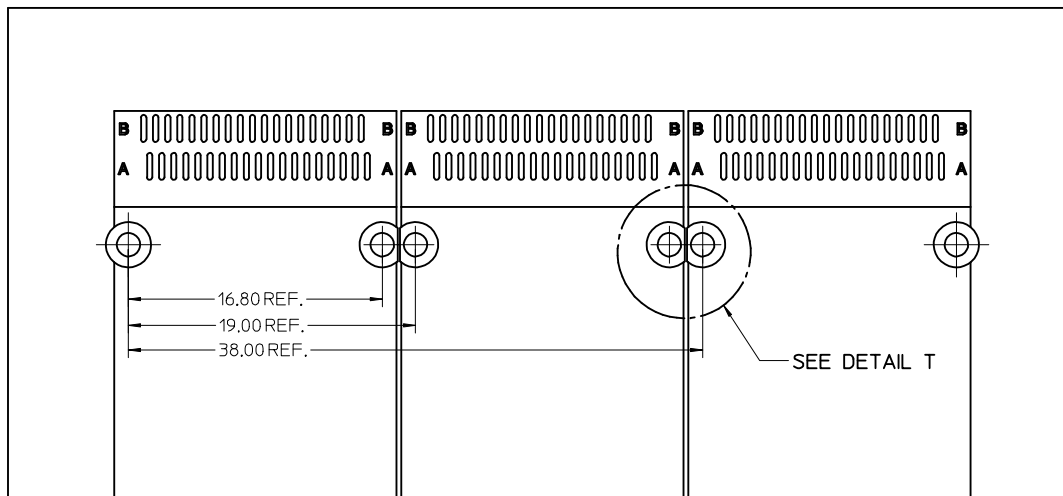
SOLDER FOOT: ~90% OF PAD
SOLDER RING: ~45% OF PAD



CIRCUIT SIZE	TERM/SIDE 'N'	DIMENSIONS		
		PEG TO PEG	CENTERLINE TO PAD	CENTERLINE TO PAD
		DIM 'A'	DIM 'C'	DIM 'D'
26	13	12.00	4.60	5.00
38	19	16.80	7.00	7.40
68	34	26.80	13.00	13.40

SEE SHEET 1 EC NO: UCP2015-0453 DRAWN BY: DRWNBINGHAM 2014/07/31 CHKD: TMCLELLAND 2014/08/01 APPR: TMCLELL 2014/08/01 C2	QUALITY SYMBOLS	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
				mm	INCH	DRAWN BY KLANG	DATE 12/06/2006	TITLE	
			4 PLACES ± --- ± ---	CHECKED BY JWENSON	DATE 12/06/2006	IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING molex			
			3 PLACES ± --- ± ---	APPROVED BY MBANAKIS	DATE 12/06/2006				
			2 PLACES ± 0.13 ± ---	MATERIAL NO.	DOCUMENT NO.				
			1 PLACE ± 0.25 ± ---	SEE CHART	SD-75586-005				
			0 PLACE ± ±	SIZE C	5 OF 6				
			ANGULAR ± 1/2°		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						
			REV						

38 CIRCUIT GANGED ON 19.00 mm CENTERLINE



NOTES:

1. STENCIL RECOMMENDATION IS A GUIDELINE ONLY.
2. MANUFACTURING PROCESS PARAMETERS WILL DEFINE THE ACTUAL STENCIL DEFINITION.
3. RECOMMENDED STENCIL THICKNESS IS 0.13MM.

SEE SHEET 1 EC NO: UCP2015-0453 DRAWN BY: DRWNBINGHAM 2014/07/31 CHKD: TMCLELLAND 2014/08/01 APPR: TMCLELLAND 2014/08/01	REV	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
							DRAWN BY DATE		TITLE			
				4 PLACES ± --- ± ---			KLANG 12/06/2006		IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING molex			
				3 PLACES ± --- ± ---			CHECKED BY DATE					
				2 PLACES ± 0.13 ± ---			JSWENSON 12/06/2006					
				1 PLACE ± 0.25 ± ---			APPROVED BY DATE					
				0 PLACE ± ±			MBANAKIS 12/06/2006					
				ANGULAR ±1/2°			MATERIAL NO.		DOCUMENT NO.			SHEET NO.
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE CHART		SD-75586-005			6 OF 6
				SIZE C			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					